

Repair assemblies professionally and price-consciously.

Technical highlights:

- 900 W Hybrid high power heating element
- Full-area 1,600 W IR bottom heater
- High-resolution cameras for placement and process monitoring
- Ergonomically optimal system operation
- Modern, user-friendly operating software



Ersa HR 500 – rework of standard electronic assemblies.

The Ersas HR 500 Hybrid Rework System is the first choice for all common rework tasks on medium-sized SMD assemblies. The system is suitable for desoldering, placing and soldering PLCC, QFP and BGA components as well as MLF components or bipolar elements up to an edge length of 1 x 1 mm.

Like all Ersas Hybrid Rework systems, the HR 500 is equipped with a powerful hybrid top heater and highly dynamic infrared heating elements in the bottom emitter (in two switchable zones).

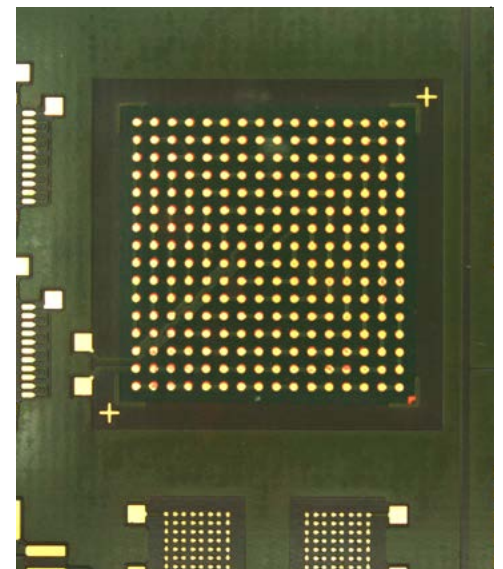
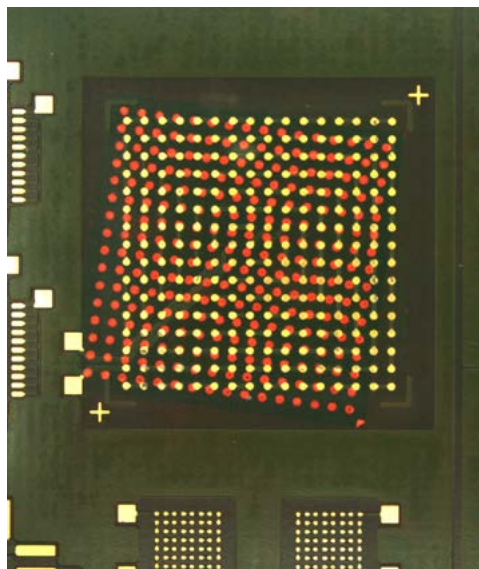
The component alignment is carried out by means of fine drives and high-resolution camera images of the Visionbox. The component is set down almost powerlessly with the aid of a stepper motor with fine switch-off. The device convinces overall by its intuitive operation and the flexibility in the Application

The HR 500 is prepared to accept an Ersas Dip & Print frame, the component printing with solder paste is done externally on the Ersas Dip & Print

Station. The dip-in of a component into a flux depot is motor-driven. For process observation and documentation, the device can optionally be equipped with a powerful reflow process camera with LED illumination.

The HRSOft 2 operating software (for Windows™) supports the user in all work processes and documents them. HRSOft 2 allows the connection of Ersas Rework devices to customer MES systems.

Component alignment of a BGA on the HR 500.



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Technical data:	
Dimensions (W x D x H):	655 x 645 x 710 mm
Weight	approx. 55 kg
Antistatic version	yes
Nominal power	2.500 W
Nonminal voltage	220 V – 240 VAC, 50 – 60 Hz, 16 A
Top heater	Hybrid emitter 900 W, 70 x 70 mm
Bottom heater	IR emitter (2 x 800 W), 270 x 270 mm
Measurement channels	2 x K-Typ
Position laser	Class II
Board size	up to 380 x 300 mm (+x), 14.9 x 11.8 inch
Component size	from 1 x 1 mm, 0.04 x 0.04 inch up to 50 x 50 mm, 1.97 x 1.97 inch
Working depths	340 mm
Working distance	60 mm to top heater, 35 mm to bottom heater
Placement camera	5 MP GigE colour camera, field of vision 50 x 50 mm
Certification mark	CE
Operating software	HRSOft 2 – suitable for Windows 8 and Windows 10
Option – Reflow process camera	2,3 MP, CMOS GigE colour camera, 25 mm focal length, illumination 2 x LED, adjustable

Order information:

Order number	description
OHR500	Ersa HR 500 Hybrid Rework System
OHR510	RPC Kamera HR 550
OPR100	Dip&Print Station complete



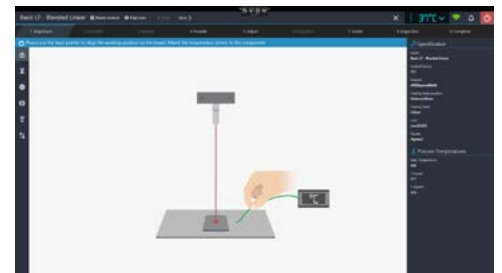
further information on our website



Ersa HR 500 Hybrid Rework System – professional module repair for budget-oriented users.



Optional Reflow process camera.



HRSOft 2 with integrated user guidance.



Flexible PCB holder.